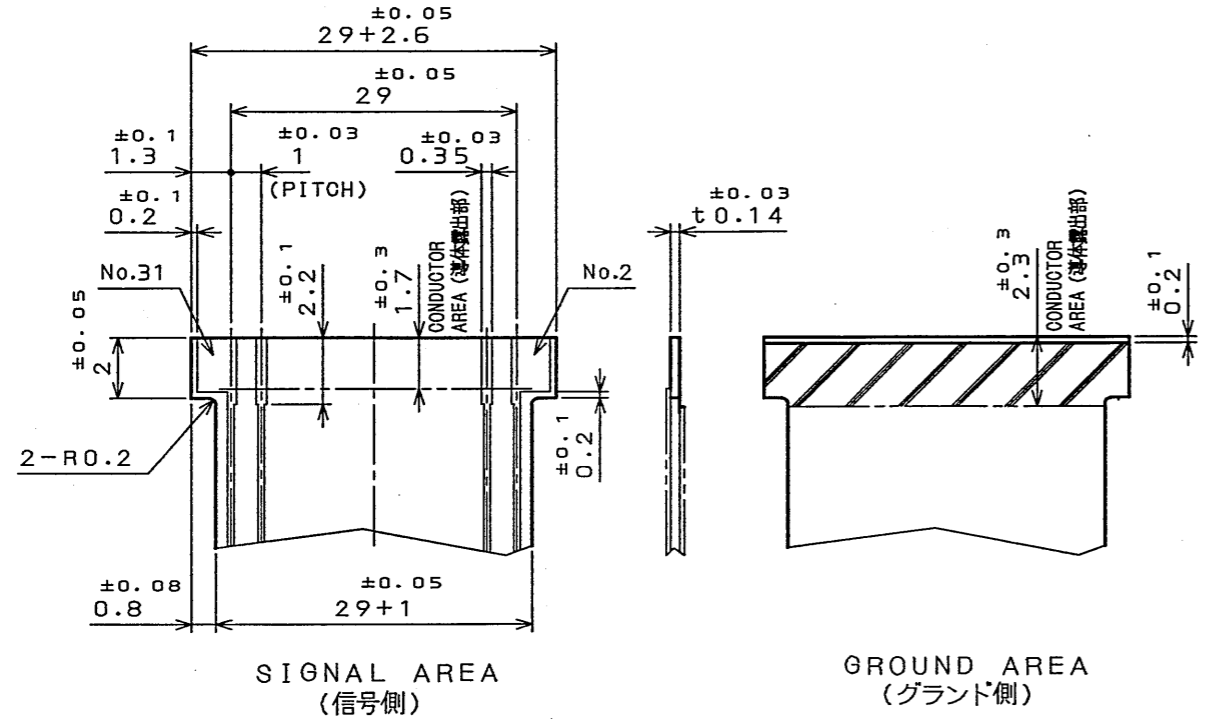
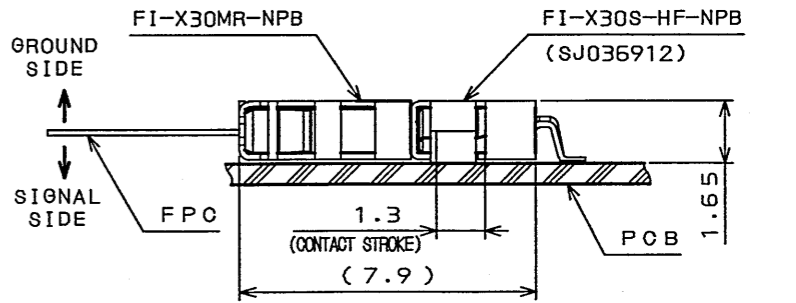
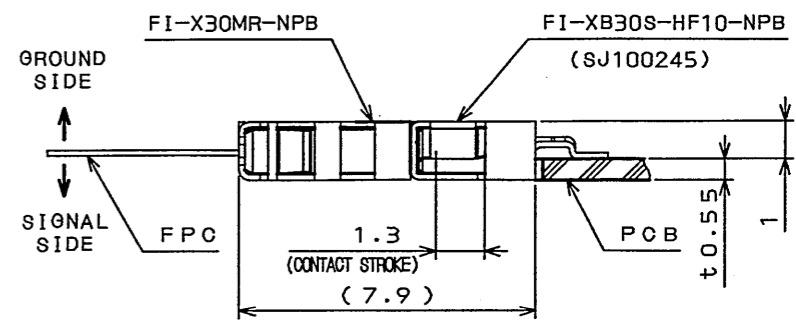
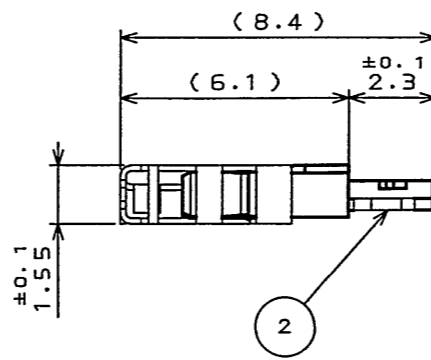
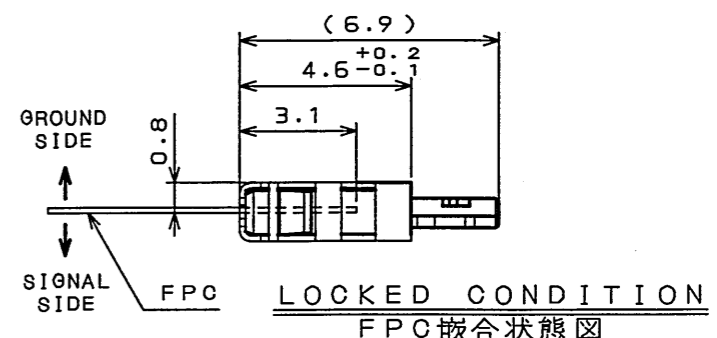
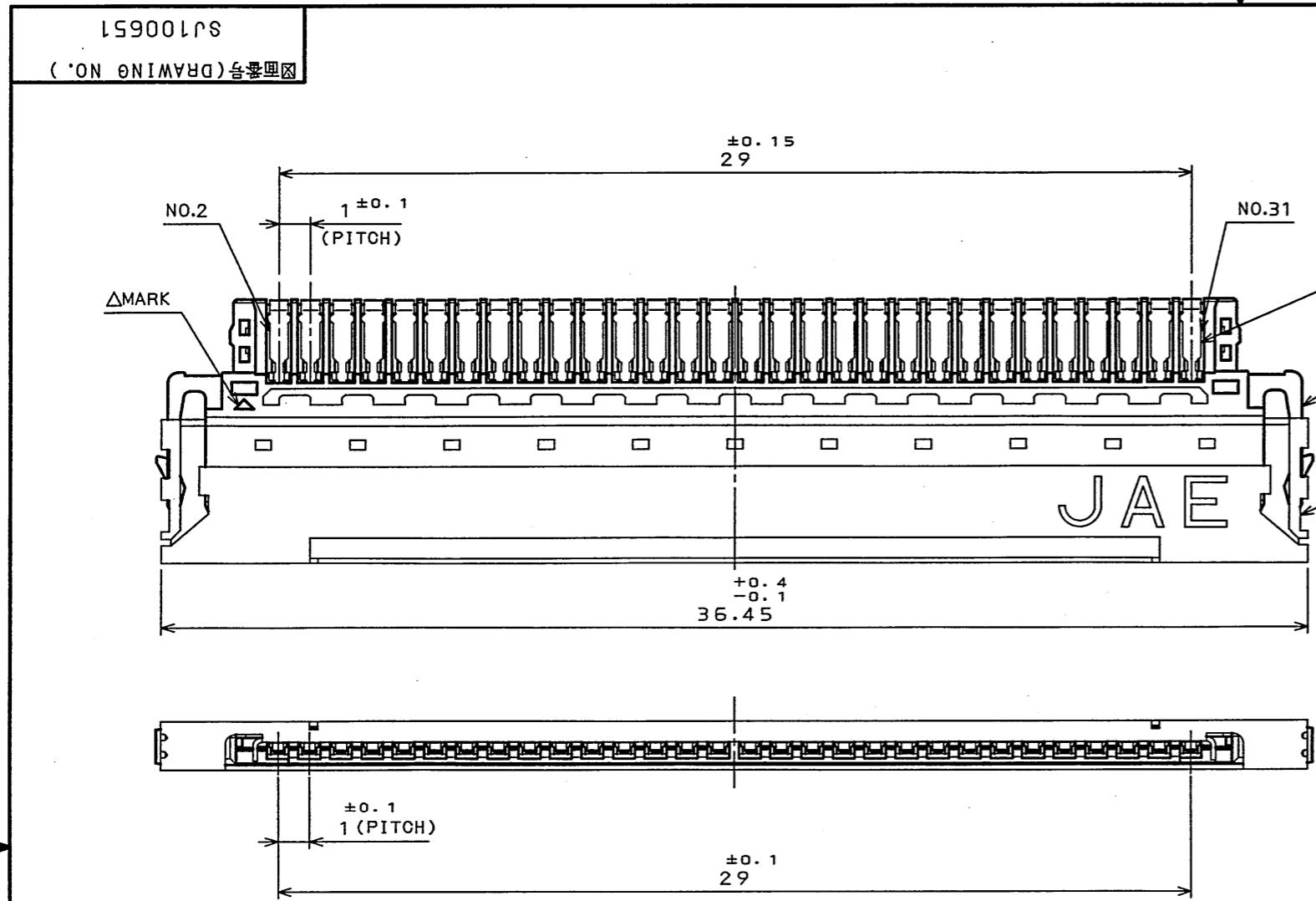


版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.



APPLICABLE FPC DIMENSIONS (REF.)
適合 FPC 寸法 (参考)

符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	SHELL	1	COPPER ALLOY	TIN PLATING	
3	INSULATOR	1	GLASS FILLED 4-6NY		UL94 V-0 BEIGE
2	GROUND PLATE	1	COPPER ALLOY	TIN PLATING	
1	CONTACT	30	COPPER ALLOY	GOLD(0.1μmMIN) OVER NICKEL	MATING FPC AREA: (LEAD FREE)TIN/TIN ALLOY OVER NICKEL

仕様書 (SPECIFICATION)	第1版 (ORIGINAL DATE) 28.Jan.2004	尺度 (SCALE) 3:1	製図 (DRAWING NO.) SJ100651
製図 (DRAWING NO.) DR.	H.SAKURADA	名称 (TITLE) FI-X30MR-NPB (FPC SIDE REVERSE TYPE)	日本航空電子工業株式会社 Reference Only JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
公差 (GENERAL TOLERANCE)	担当 (CHK.) T.YAMAJI	重量 (WEIGHT)	図面番号 (DRAWING NO.) SJ100651
寸法 (DIMENSION)	査閲 (APPD.) M. Suzuki	承認 (APPD.) Y. Chiyama	版数 (REV.) 1
角度 (ANGLES)			
. ±0.8	X° ±		
.X ±0.4	X°X' ±		
.XX ±0.1			
.XXX ±			

LEAD FREE この製品は鉛フリー品です

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